ABSTRACT

METHOD OF FABRICATING MEMS DEVICES ON A SILICON WAFER

A method of fabricating MEMS devices is provided. The method including the steps of: (a) providing a silicon wafer having a MEMS layer arranged on one side of the wafer; (b) applying a first holding means to the MEMS layer; (c) performing at least one operation on the wafer from a side of the wafer opposed to the side having the MEMS layer; (d) applying a second holding means to said opposed side of the wafer; (e) removing the first holding means; (f) performing at least one deep silicon etch on the MEMS layer to define individual MEMS chips, each chip being composed of a part of the wafer and at least one part of the MEMS layer; and (g) causing the individual chips to be released from the second holding means for removal from the second holding means.

Figure 6